

Due to the high deformation resistance and resilience of **harpress** contacts, they can be easily and repeatedly removed in case of repairs without impairment to their functioning.

Today tinned surfaces are widely used as a standard, the pcb technology trends are moving to low tin or tin free surfaces. Cu, Pd, Au and Ag are the important alternatives. Specific parameters and particularly different friction factors of these surfaces make high demands on press-in zones.

harpress is extremely versatile and offers a reliable electrical contact, therefore it is especially well suited for applications with these surfaces.

Please contact us for detailed test reports.

Benefits of the press-in technology

- Thermal shocks associated with the soldering process and the risk of the board malfunction are avoided.
- No need for the subsequent cleaning of the assembled pcb's

Recommended configuration chart for tinned plated through holes

	Plated through hole	
	0.6 mm	1 mm
Drilled hole Ø [mm]	0.71 - 0.74	1.12 - 1.15
Cu thickness [µm]	30 - 60	25 - 75
Sn thickness [µm]	5 - 20	5 - 15
Plated hole Ø [mm]	0.55 - 0.67	0.94 - 1.09
Board thickness [mm]	1.6 - 3.2	1.6 - 3.2
Connector range	har-mik	SEK and D-Sub

